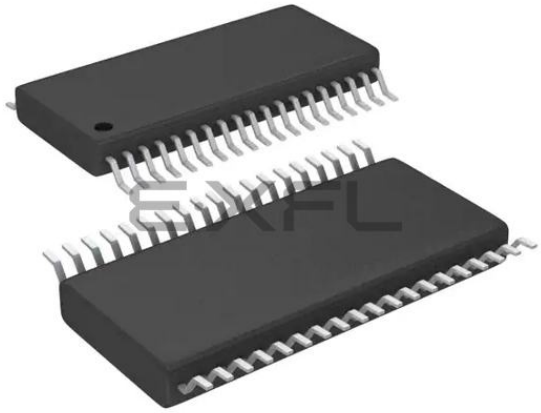

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	XC800
Core Size	8-Bit
Speed	86MHz
Connectivity	SSI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	19
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	38-TFSOP (0.173", 4.40mm Width)
Supplier Device Package	PG-TSSOP-38
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/sak-xc866-2fri-bc

XC866

8-Bit Single-Chip Microcontroller

Microcontrollers

Never stop thinking

2.4 Pin Definitions and Functions

Table 3 Pin Definitions and Functions

Symbol	Pin Number	Type	Reset State	Function
P0		I/O		**Port 0** Port 0 is a 6-bit bidirectional general purpose I/O port. It can be used as alternate functions for the JTAG, CCU6, UART, and the SSC.
P0.0	12		Hi-Z	TCK_0 JTAG Clock Input T12HR_1 CCU6 Timer 12 Hardware Run Input CC61_1 Input/Output of Capture/Compare channel 1 CLKOUT Clock Output RXDO_1 UART Transmit Data Output
P0.1	14		Hi-Z	TDI_0 JTAG Serial Data Input T13HR_1 CCU6 Timer 13 Hardware Run Input RXD_1 UART Receive Data Input COUT61_1 Output of Capture/Compare channel 1 EXF2_1 Timer 2 External Flag Output
P0.2	13		PU	$\overline{\text{CTRAP}}$_2 CCU6 Trap Input TDO_0 JTAG Serial Data Output TXD_1 UART Transmit Data Output/ Clock Output
P0.3	2		Hi-Z	SCK_1 SSC Clock Input/Output COUT63_1 Output of Capture/Compare channel 3
P0.4	3		Hi-Z	MTSR_1 SSC Master Transmit Output/ Slave Receive Input CC62_1 Input/Output of Capture/Compare channel 2
P0.5	4		Hi-Z	MRST_1 SSC Master Receive Input/ Slave Transmit Output EXINT0_0 External Interrupt Input 0 COUT62_1 Output of Capture/Compare channel 2

3.2.1 Memory Protection Strategy

The XC866 memory protection strategy includes:

- Read-out protection: The Flash Memory can be enabled for read-out protection and ROM memory is always protected.
- Program and erase protection: The Flash memory in all devices can be enabled for program and erase protection.

Flash memory protection is available in two modes:

- Mode 0: Only the P-Flash is protected; the D-Flash is unprotected
- Mode 1: Both the P-Flash and D-Flash are protected

The selection of each protection mode and the restrictions imposed are summarized in **Table 4**.

Table 4 Flash Protection Modes

Mode	0	1
Activation	Program a valid password via BSL mode 6	
Selection	MSB of password = 0	MSB of password = 1
P-Flash contents can be read by	Read instructions in the P-Flash	Read instructions in the P-Flash or D-Flash
P-Flash program and erase	Not possible	Not possible
D-Flash contents can be read by	Read instructions in any program memory	Read instructions in the P-Flash or D-Flash
D-Flash program	Possible	Not possible
D-Flash erase	Possible, on the condition that bit DFLASHEN in register MISC_CON is set to 1 prior to each erase operation	Not possible

BSL mode 6, which is used for enabling Flash protection, can also be used for disabling Flash protection. Here, the programmed password must be provided by the user. A password match triggers an automatic erase of the read-protected Flash contents, see **Table 5** and **Table 6**, and the programmed password is erased. The Flash protection is then disabled upon the next reset.

For XC866-2FR and XC866-4FR devices:

The selection of protection type is summarized in **Table 5**.

Note: The RMAP bit must be cleared/set by ANL or ORL instructions. The rest bits of SYSCON0 should not be modified.

As long as bit RMAP is set, the mapped SFR area can be accessed. This bit is not cleared automatically by hardware. Thus, before standard/mapped registers are accessed, bit RMAP must be cleared/set, respectively, by software.

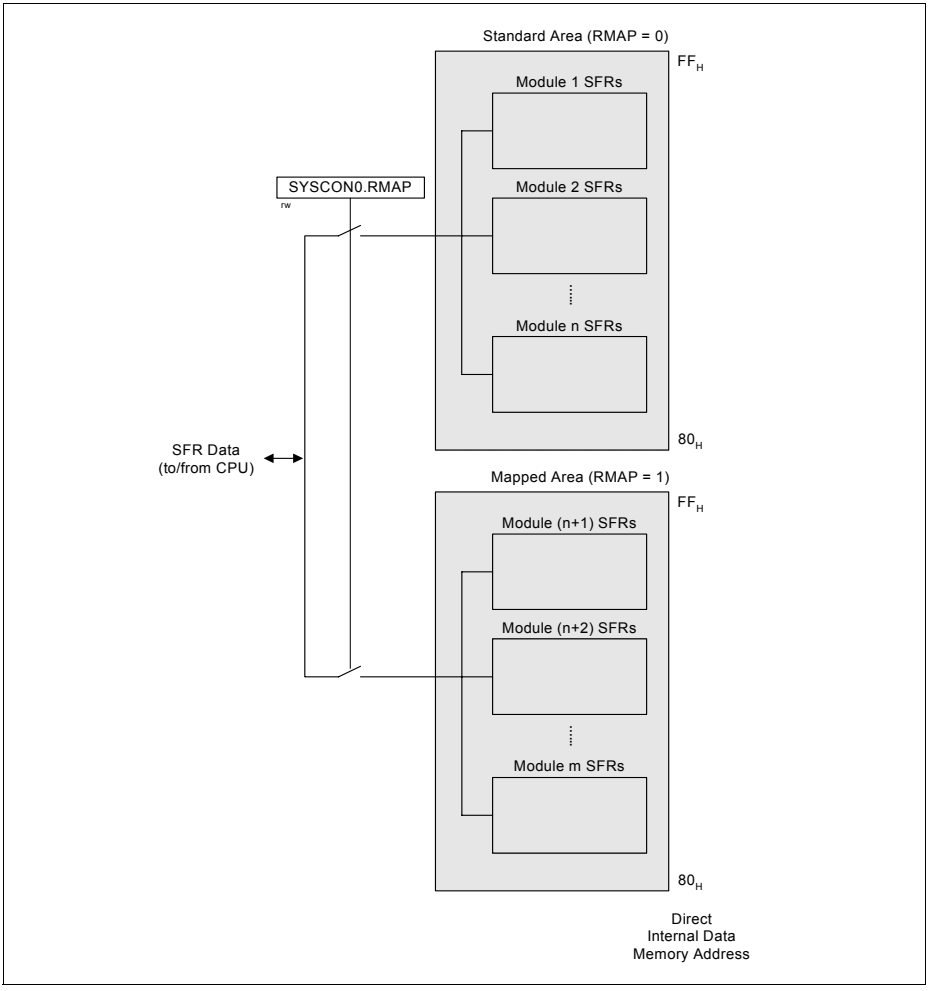

Figure 8 Address Extension by Mapping

3.2.2.2 Address Extension by Paging

Address extension is further performed at the module level by paging. With the address extension by mapping, the XC866 has a 256-SFR address range. However, this is still less than the total number of SFRs needed by the on-chip peripherals. To meet this requirement, some peripherals have a built-in local address extension mechanism for increasing the number of addressable SFRs. The extended address range is not directly controlled by the CPU instruction itself, but is derived from bit field PAGE in the module page register MOD_PAGE. Hence, the bit field PAGE must be programmed before accessing the SFR of the target module. Each module may contain a different number of pages and a different number of SFRs per page, depending on the specific requirement. Besides setting the correct RMAP bit value to select the SFR area, the user must also ensure that a valid PAGE is selected to target the desired SFR. A page inside the extended address range can be selected as shown in **Figure 9**.

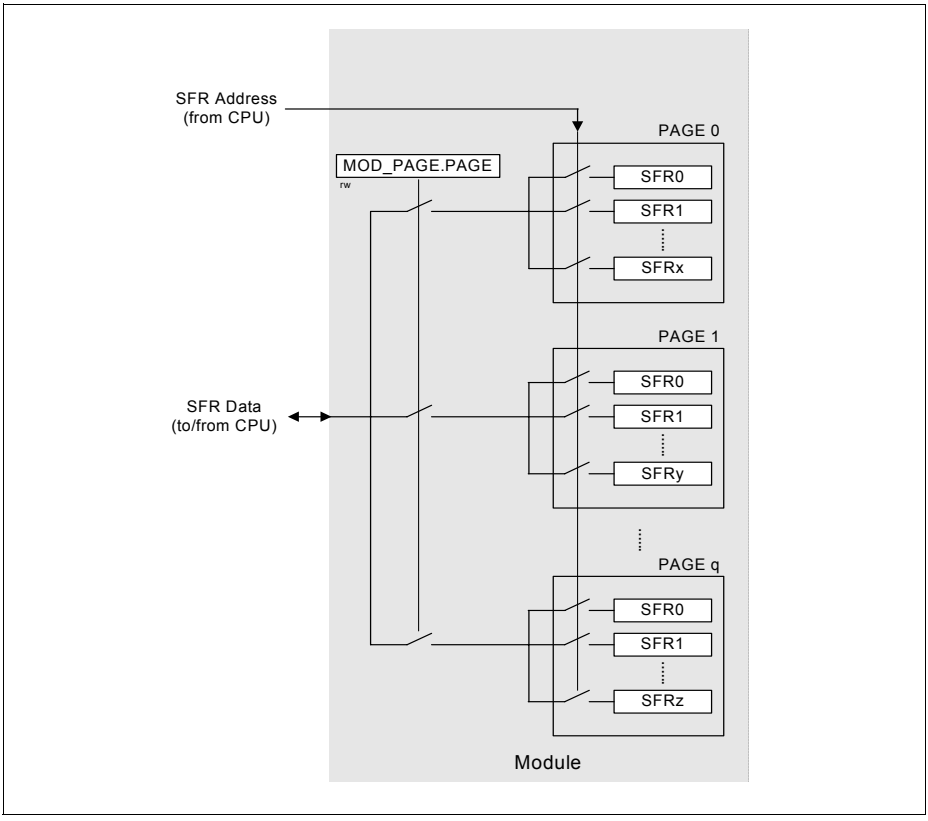

Figure 9 Address Extension by Paging

Table 14 SSC Register Overview

AB_H	**SSC_CONH** **Reset: 00_H** Control Register High *Programming Mode*	Bit Field	EN	MS	0	AREN	BEN	PEN	REN	TEN
		Type	rw	rw	r	rw	rw	rw	rw	rw
	Operating Mode	Bit Field	EN	MS	0	BSY	BE	PE	RE	TE
		Type	rw	rw	r	rh	rwh	rwh	rwh	rwh
AC_H	**SSC_TBL** **Reset: 00_H** Transmitter Buffer Register Low	Bit Field	TB_VALUE							
		Type	rw							
AD_H	**SSC_RBL** **Reset: 00_H** Receiver Buffer Register Low	Bit Field	RB_VALUE							
		Type	rh							
AE_H	**SSC_BRL** **Reset: 00_H** Baudrate Timer Reload Register Low	Bit Field	BR_VALUE[7:0]							
		Type	rw							
AF_H	**SSC_BRH** **Reset: 00_H** Baudrate Timer Reload Register High	Bit Field	BR_VALUE[15:8]							
		Type	rw							

The OCDS SFRs can be accessed in the mapped memory area (RMAP = 1).

Table 15 OCDS Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 1										
$E9_H$	**MMCR2** **Reset: $0U_H$** Monitor Mode Control Register 2	Bit Field	EXBC_P	EXBC	MBCON_P	MBCON	MMEP_P	MMEP	MMODE	JENA
		Type	w	rw	w	rwh	w	rwh	rh	rh
$F1_H$	**MMCR** **Reset: 00_H** Monitor Mode Control Register	Bit Field	MEXIT_P	MEXIT	MSTEP_P	MSTEP	MRAMS_P	MRAMS	TRF	RRF
		Type	w	rwh	w	rw	w	rwh	rh	rh
$F2_H$	**MMSR** **Reset: 00_H** Monitor Mode Status Register	Bit Field	MBCAM	MBCIN	EXBF	SWBF	HWB3F	HWB2F	HWB1F	HWB0F
		Type	rw	rh	rwh	rwh	rwh	rwh	rwh	rwh
$F3_H$	**MMBPCR** **Reset: 00_H** BreakPoints Control Register	Bit Field	SWBC	HWB3C		HWB2C		HWB1C	HWB0C	
		Type	rw	rw		rw		rw	rw	
$F4_H$	**MMICR** **Reset: 00_H** Monitor Mode Interrupt Control Register	Bit Field	DVECT	DRETR	0		MMUIE_P	MMUIE	RRIE_P	RRIE
		Type	rwh	rwh	r		w	rw	w	rw
$F5_H$	**MMDR** **Reset: 00_H** Monitor Mode Data Register *Receive*	Bit Field	MMRR							
		Type	rh							
	Transmit	Bit Field	MMTR							
		Type	w							
$F6_H$	**HWBPSR** **Reset: 00_H** Hardware Breakpoints Select Register	Bit Field	0			BPSEL_P	BPSEL			
		Type	r			w	rw			
$F7_H$	**HWBPDR** **Reset: 00_H** Hardware Breakpoints Data Register	Bit Field	HWBPxx							
		Type	rw							

3.3 Flash Memory

The Flash memory provides an embedded user-programmable non-volatile memory, allowing fast and reliable storage of user code and data. It is operated from a single 2.5 V supply from the Embedded Voltage Regulator (EVR) and does not require additional programming or erasing voltage. The sectorization of the Flash memory allows each sector to be erased independently.

Features

- In-System Programming (ISP) via UART
- In-Application Programming (IAP)
- Error Correction Code (ECC) for dynamic correction of single-bit errors
- Background program and erase operations for CPU load minimization
- Support for aborting erase operation
- Minimum program width[1] of 32-byte for D-Flash and 32-byte for P-Flash
- 1-sector minimum erase width
- 1-byte read access
- Flash is delivered in erased state (read all zeros)
- Operating supply voltage: 2.5 V ± 7.5 %
- Read access time: 3 × t_{CCLK} = 112.5 ns[2]
- Program time: 209440 / f_{SYS} = 2.6 ms[3]
- Erase time: 8175360 / f_{SYS} = 102 ms[3]

1) P-Flash: 32-byte wordline can only be programmed once, i.e., one gate disturb allowed.
D-Flash: 32-byte wordline can be programmed twice, i.e., two gate disturbs allowed.

2) f_{sys} = 80 MHz ± 7.5% (f_{CCLK} = 26.7 MHz ± 7.5 %) is the maximum frequency range for Flash read access.

3) f_{sys} = 80 MHz ± 7.5% is the only frequency range for Flash programming and erasing. f_{sysmin} is used for obtaining the worst case timing.

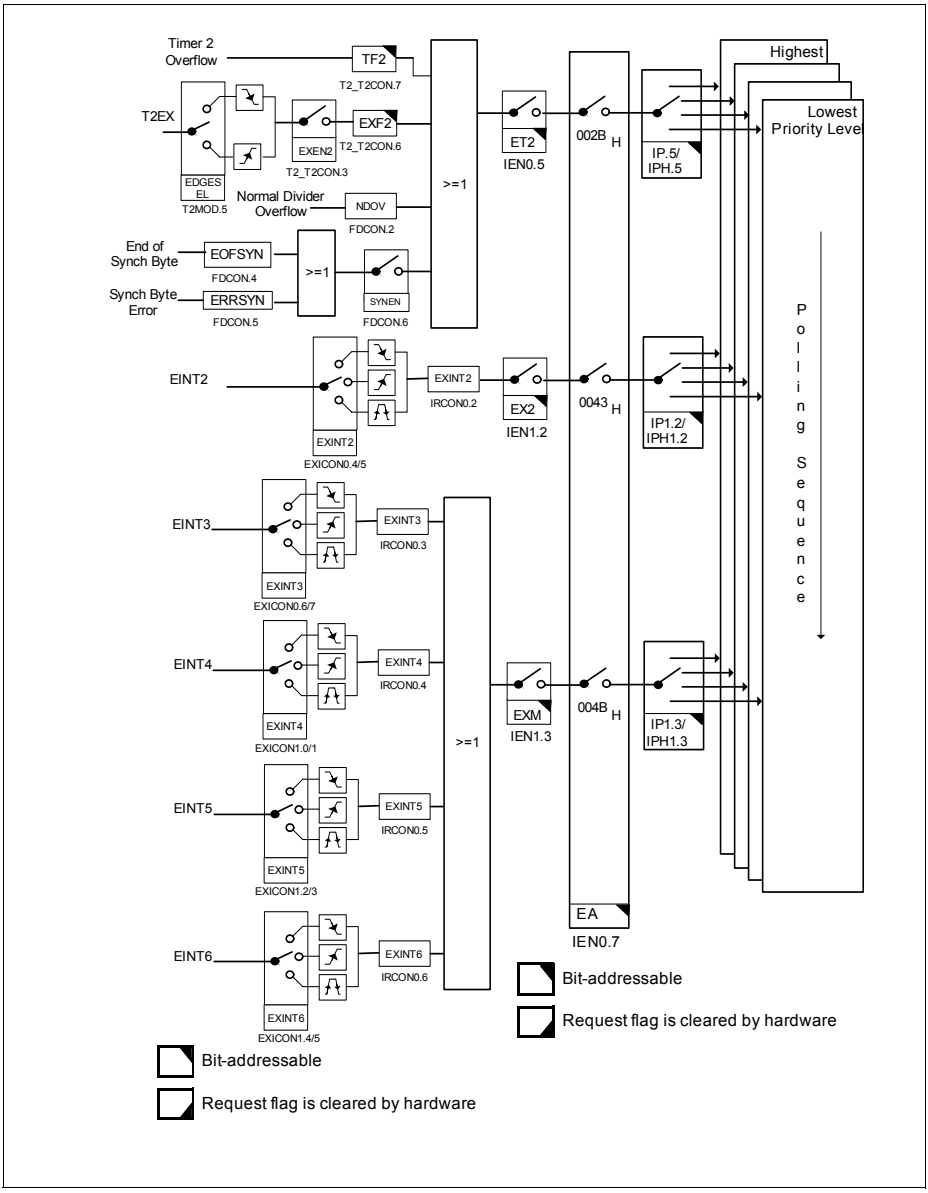

Figure 15 Interrupt Request Sources (Part 2)

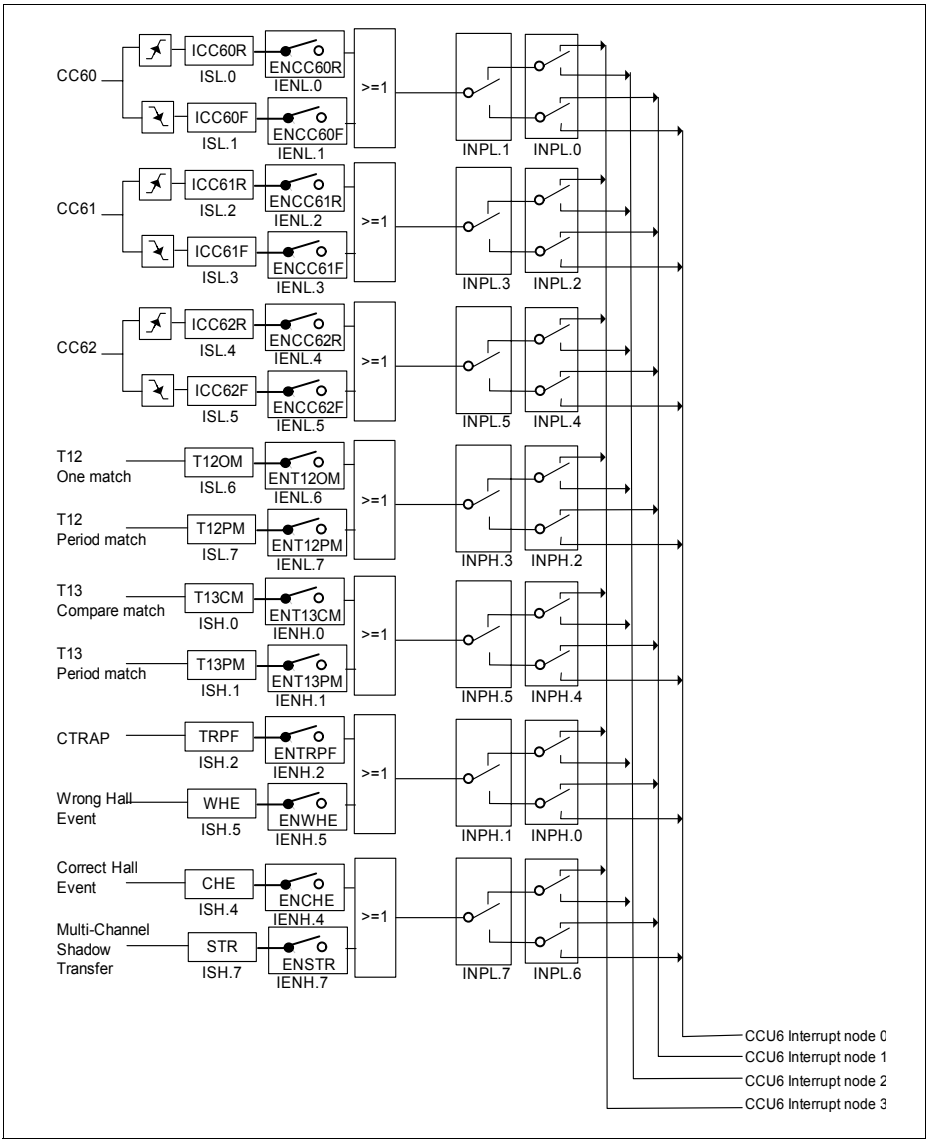

Figure 17 Interrupt Request Sources (Part 4)

3.4.3 Interrupt Priority

Each interrupt source, except for NMI, can be individually programmed to one of the four possible priority levels. The NMI has the highest priority and supersedes all other interrupts. Two pairs of interrupt priority registers (IP and IPH, IP1 and IPH1) are available to program the priority level of each non-NMI interrupt vector.

A low-priority interrupt can be interrupted by a high-priority interrupt, but not by another interrupt of the same or lower priority. Further, an interrupt of the highest priority cannot be interrupted by any other interrupt source.

If two or more requests of different priority levels are received simultaneously, the request of the highest priority is serviced first. If requests of the same priority are received simultaneously, then an internal polling sequence determines which request is serviced first. Thus, within each priority level, there is a second priority structure determined by the polling sequence shown in **Table 18**.

Table 18 Priority Structure within Interrupt Level

Source	Level
Non-Maskable Interrupt (NMI)	(highest)
External Interrupt 0	1
Timer 0 Interrupt	2
External Interrupt 1	3
Timer 1 Interrupt	4
UART Interrupt	5
Timer 2, Fractional Divider, LIN Interrupts	6
ADC Interrupt	7
SSC Interrupt	8
External Interrupt 2	9
External Interrupt [6:3]	10
CCU6 Interrupt Node Pointer 0	11
CCU6 Interrupt Node Pointer 1	12
CCU6 Interrupt Node Pointer 2	13
CCU6 Interrupt Node Pointer 3	14

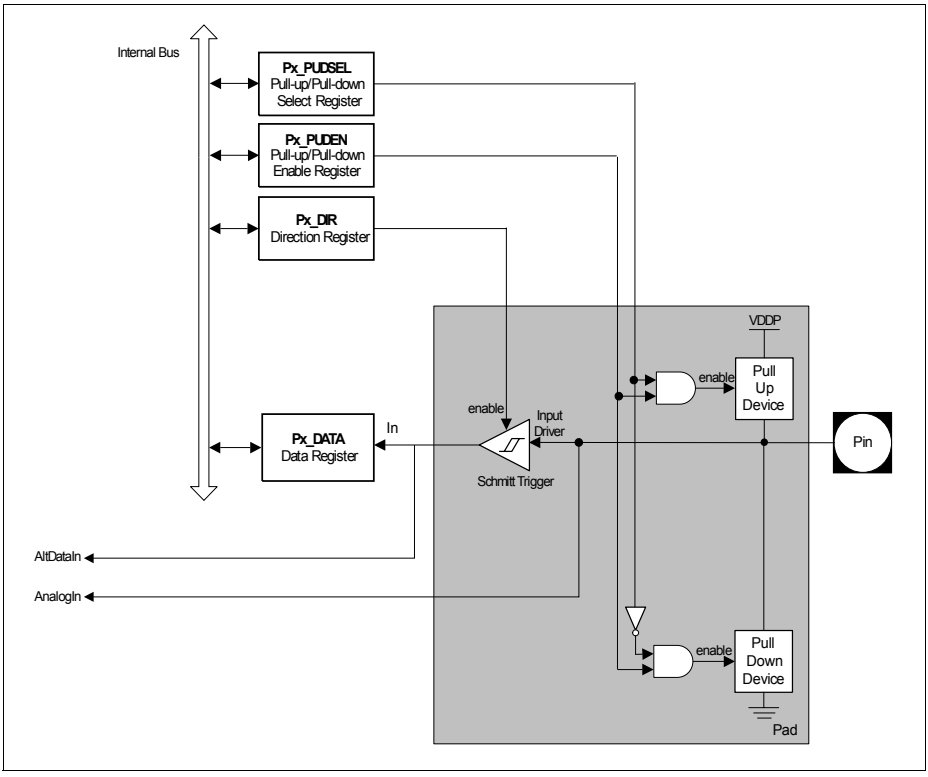

Figure 19 General Structure of Input Port

3.7 Reset Control

The XC866 has five types of reset: power-on reset, hardware reset, watchdog timer reset, power-down wake-up reset, and brownout reset.

When the XC866 is first powered up, the status of certain pins (see **Table 20**) must be defined to ensure proper start operation of the device. At the end of a reset sequence, the sampled values are latched to select the desired boot option, which cannot be modified until the next power-on reset or hardware reset. This guarantees stable conditions during the normal operation of the device.

In order to power up the system properly, the external reset pin $\overline{\text{RESET}}$ must be asserted until V_{DDC} reaches 0.9*V_{DDC}. The delay of external reset can be realized by an external capacitor at $\overline{\text{RESET}}$ pin. This capacitor value must be selected so that V_{RESET} reaches 0.4 V, but not before V_{DDC} reaches 0.9* V_{DDC}.

A typical application example is shown in **Figure 21**. V_{DDP} capacitor value is 300 nF. V_{DDC} capacitor value is 220 nF. The capacitor connected to $\overline{\text{RESET}}$ pin is 100 nF.

Typically, the time taken for V_{DDC} to reach 0.9*V_{DDC} is less than 50 µs once V_{DDP} reaches 2.3V. Hence, based on the condition that 10% to 90% V_{DDP} (slew rate) is less than 500 µs, the $\overline{\text{RESET}}$ pin should be held low for 500 µs typically. See **Figure 22**.

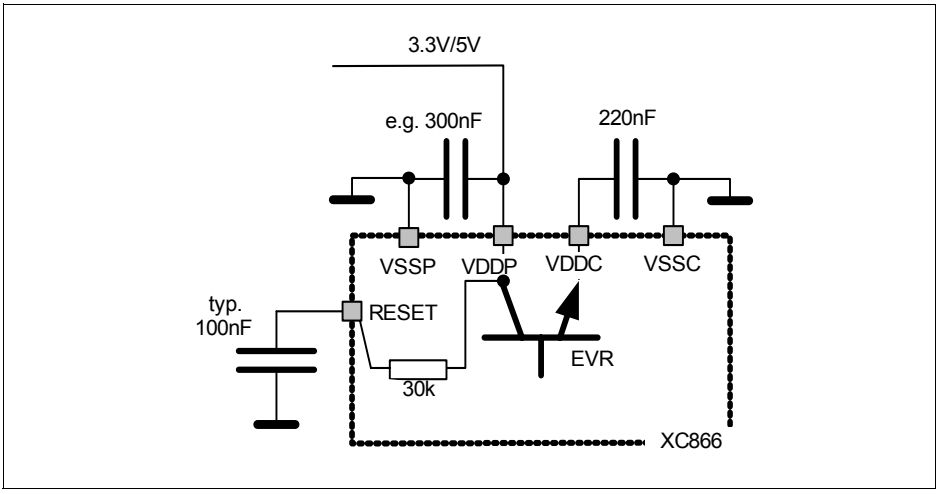

Figure 21 Reset Circuitry

3.7.1 Module Reset Behavior

Table 19 shows how the functions of the XC866 are affected by the various reset types. A "■" means that this function is reset to its default state.

Table 19 Effect of Reset on Device Functions

Module/ Function	Wake-Up Reset	Watchdog Reset	Hardware Reset	Power-On Reset	Brownout Reset
CPU Core	■	■	■	■	■
Peripherals	■	■	■	■	■
On-Chip Static RAM	Not affected, reliable	Not affected, reliable	Not affected, reliable	Affected, un-reliable	Affected, un-reliable
Oscillator, PLL	■	Not affected	■	■	■
Port Pins	■	■	■	■	■
EVR	The voltage regulator is switched on	Not affected	■	■	■
FLASH	■	■	■	■	■
NMI	Disabled	Disabled	■	■	■

3.7.2 Booting Scheme

When the XC866 is reset, it must identify the type of configuration with which to start the different modes once the reset sequence is complete. Thus, boot configuration information that is required for activation of special modes and conditions needs to be applied by the external world through input pins. After power-on reset or hardware reset, the pins MBC, TMS and P0.0 collectively select the different boot options. Table 20 shows the available boot options in the XC866.

Table 20 XC866 Boot Selection

MBC	TMS	P0.0	Type of Mode	PC Start Value
1	0	x	User Mode; on-chip OSC/PLL non-bypassed	0000_H
0	0	x	BSL Mode; on-chip OSC/PLL non-bypassed	0000_H
0	1	0	OCDS Mode[1]; on-chip OSC/PLL non-bypassed	0000_H
1	1	0	Standalone User (JTAG) Mode[2]; on-chip OSC/PLL non-bypassed (normal)	0000_H

1) The OCDS mode is not accessible if Flash is protected.
2) Normal user mode with standard JTAG (TCK,TDI,TDO) pins for hot-attach purpose.

3.9 Power Saving Modes

The power saving modes of the XC866 provide flexible power consumption through a combination of techniques, including:

- Stopping the CPU clock
- Stopping the clocks of individual system components
- Reducing clock speed of some peripheral components
- Power-down of the entire system with fast restart capability

After a reset, the active mode (normal operating mode) is selected by default (see **Figure 26**) and the system runs in the main system clock frequency. From active mode, different power saving modes can be selected by software. They are:

- Idle mode
- Slow-down mode
- Power-down mode

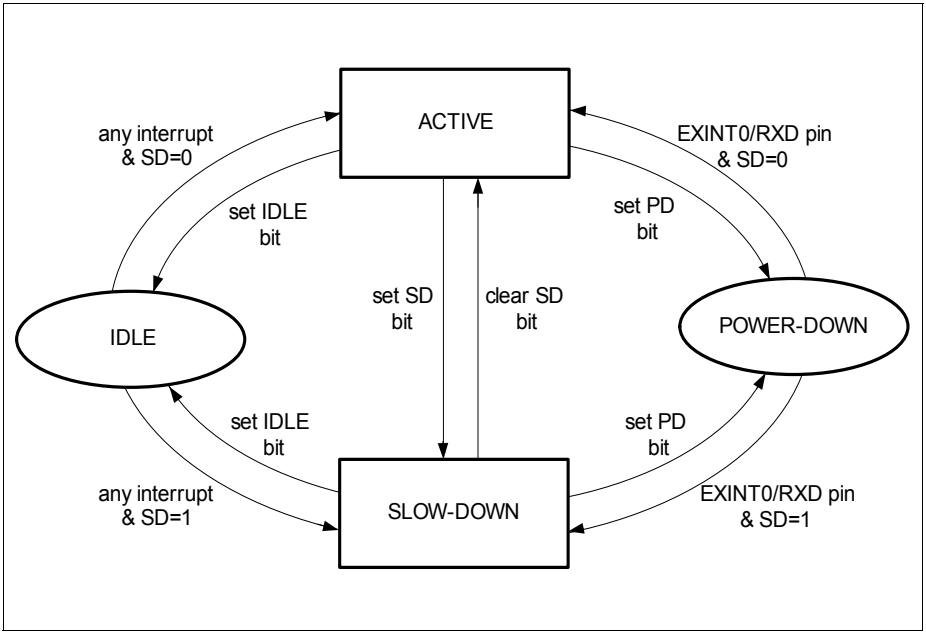

Figure 26 Transition between Power Saving Modes

3.16 Timer 2

Timer 2 is a 16-bit general purpose timer (THL2) that has two modes of operation, a 16-bit auto-reload mode and a 16-bit one channel capture mode. If the prescalar is disabled, Timer 2 counts with an input clock of PCLK/12. Timer 2 continues counting as long as it is enabled.

Table 29 Timer 2 Modes

Mode	Description
Auto-reload	**Up/Down Count Disabled** • Count up only • Start counting from 16-bit reload value, overflow at $FFFF_H$ • Reload event configurable for trigger by overflow condition only, or by negative/positive edge at input pin T2EX as well • Programmble reload value in register RC2 • Interrupt is generated with reload event
	Up/Down Count Enabled • Count up or down, direction determined by level at input pin T2EX • No interrupt is generated • Count up – Start counting from 16-bit reload value, overflow at $FFFF_H$ – Reload event triggered by overflow condition – Programmble reload value in register RC2 • Count down – Start counting from $FFFF_H$, underflow at value defined in register RC2 – Reload event triggered by underflow condition – Reload value fixed at $FFFF_H$
Channel capture	• Count up only • Start counting from 0000_H, overflow at $FFFF_H$ • Reload event triggered by overflow condition • Reload value fixed at 0000_H • Capture event triggered by falling/rising edge at pin T2EX • Captured timer value stored in register RC2 • Interrupt is generated with reload or capture event

For module clock f_{ADC} = 26.7 MHz, the analog clock f_{ADCI} frequency can be selected as shown in **Table 30**.

Table 30 f_{ADCI} Frequency Selection

Module Clock f_{ADC}	CTC	Prescaling Ratio	Analog Clock f_{ADCI}
26.7 MHz	00_B	÷ 2	13.3 MHz (N.A)
	01_B	÷ 3	8.9 MHz
	10_B	÷ 4	6.7 MHz
	11_B (default)	÷ 32	833.3 kHz

As f_{ADCI} cannot exceed 10 MHz, bit field CTC should not be set to 00_B when f_{ADC} is 26.7 MHz. During slow-down mode where f_{ADC} may be reduced to 13.3 MHz, 6.7 MHz etc., CTC can be set to 00_B as long as the divided analog clock f_{ADCI} does not exceed 10 MHz. However, it is important to note that the conversion error could increase due to loss of charges on the capacitors, if f_{ADC} becomes too low during slow-down mode.

3.18.2 ADC Conversion Sequence

The analog-to-digital conversion procedure consists of the following phases:

- Synchronization phase (t_{SYN})
- Sample phase (t_S)
- Conversion phase
- Write result phase (t_{WR})

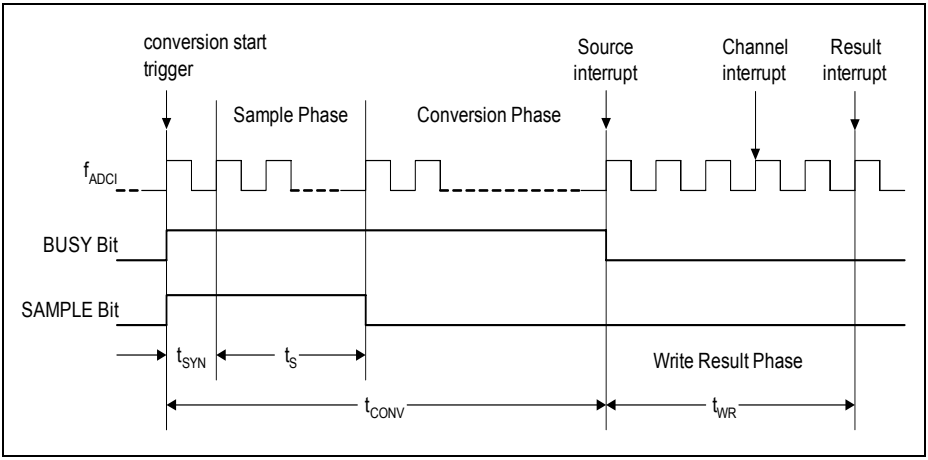

Figure 34 ADC Conversion Timing

4 Electrical Parameters

Chapter 4 provides the characteristics of the electrical parameters which are implementation-specific for the XC866.

Note: The electrical parameters are valid for the XC866-4FR and XC866-2FR. The electrical parameters for the ROM variants and XC866-1FR are preliminary, differences from XC866-4FR and XC866-2FR are stated explicitly.

4.1 General Parameters

The general parameters are described here to aid the users in interpreting the parameters mainly in **Section 4.2** and **Section 4.3**.

4.1.1 Parameter Interpretation

The parameters listed in this section represent partly the characteristics of the XC866 and partly its requirements on the system. To aid interpreting the parameters easily when evaluating them for a design, they are indicated by the abbreviations in the “Symbol” column:

- **CC**
  These parameters indicate **C**ontroller **C**haracteristics, which are distinctive features of the XC866 and must be regarded for a system design.
- **SR**
  These parameters indicate **S**ystem **R**equirements, which must be provided by the microcontroller system in which the XC866 is designed in.

4) Not subjected to production test, verified by design/characterization. However, for applications with strict low power-down current requirements, it is mandatory that no active voltage source is supplied at any GPIO pin when VDDP is powered off.

Table 36 ADC Characteristics (Operating Conditions apply; V_{DDP} = 5V Range)

Parameter	Symbol	Limit Values			Unit	Test Conditions/ Remarks
		min.	typ .	max.		
Switched capacitance at the analog voltage inputs	C_{AINSW} CC	–	5	7	pF	2)4)
Input resistance of the reference input	R_{AREF}CC	–	1	2	kΩ	2)
Input resistance of the selected analog channel	R_{AIN} CC	–	1	1.5	kΩ	2)

1) TUE is tested at V_{AREF} = 5.0 V, V_{AGND} = 0 V , V_{DDP} = 5.0 V.

2) Not subject to production test, verified by design/characterization.

3) This represents an equivalent switched capacitance. This capacitance is not switched to the reference voltage at once. Instead of this, smaller capacitances are successively switched to the reference voltage.

4) The sampling capacity of the conversion C-Network is pre-charged to V_{AREF}/2 before connecting the input to the C-Network. Because of the parasitic elements, the voltage measured at ANx is lower than V_{AREF}/2.

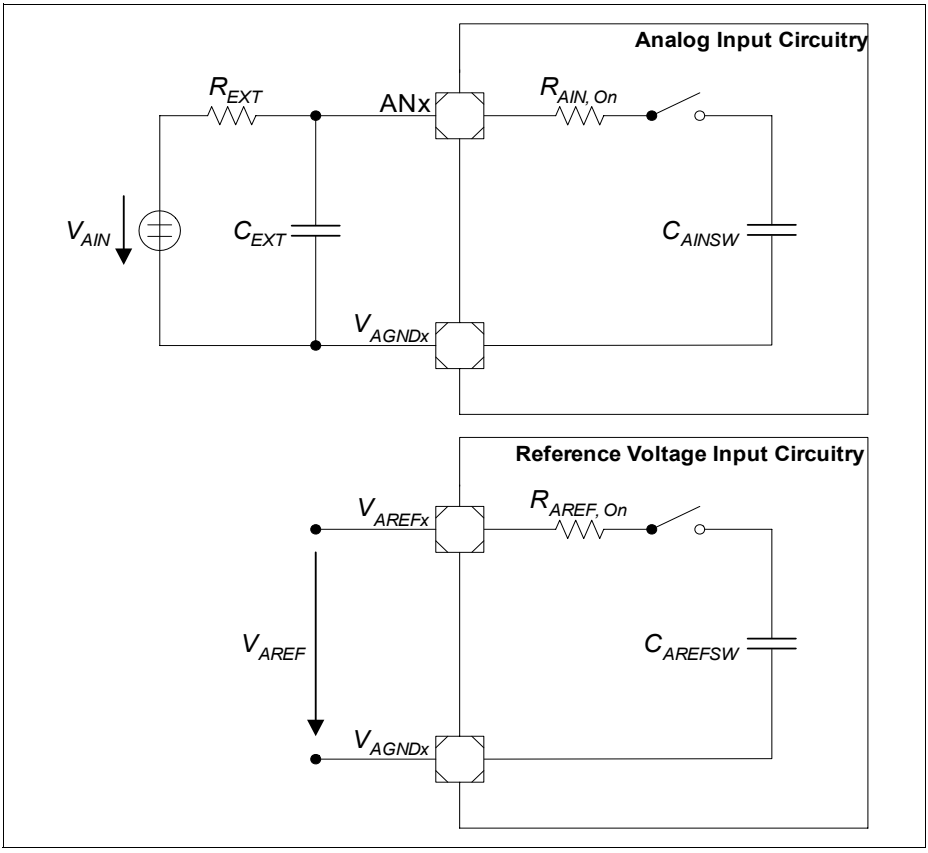

Figure 37 ADC Input Circuits

4.2.3.1 ADC Conversion Timing

Conversion time, $t_C = t_{ADC} \times (1 + r \times (3 + n + STC))$, where

r = CTC + 2 for CTC = 00_B, 01_B or 10_B,

r = 32 for CTC = 11_B,

CTC = Conversion Time Control (GLOBCTR.CTC),

STC = Sample Time Control (INPCR0.STC),

n = 8 or 10 (for 8-bit and 10-bit conversion respectively),

$t_{ADC} = 1 / f_{ADC}$